

L Number	Hits	Search Text	DB	Time stamp
34	5	("5189812" "5325604" "5458687" "5609720" "5791895").PN.	USPAT	2003/07/29 10:50
64	15	("4469529" "5108792" "5345534" "5551985" "5595606" "5624499" "5650082" "5683518" "5708755" "5711815" "5846476" "5889258" "5900177" "5937142" "5970214").PN.	USPAT	2003/07/29 12:04
65	106249	(adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 temperature near12 (antifreeze anti-freeze glycol ethyleneglycol water refrigerant (((heat near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2 exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant or (cooling near2 (fluid medium liquid gas vapor)))) (thermal near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (thermal near2 exchang\$3 near2 (fluid medium liquid gas vapor))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 12:09
66	26170	(adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near12 (((flow\$3 circulat\$3 suppl\$4) near3 (rate speed)) near8 (antifreeze anti-freeze glycol ethyleneglycol water refrigerant (((heat near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2 exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant or (cooling near2 (fluid medium liquid gas vapor)))) (thermal near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (thermal near2 exchang\$3 near2 (fluid medium liquid gas vapor))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 12:10
67	611	(adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 (power energy) near10 (process lamp ion electron) near10 (temperature near3 (wafer substrate workpiece plate susceptor pedestal support table chuck holder))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 17:00
69	18	((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near12 (((flow\$3 circulat\$3 suppl\$4) near3 (rate speed)) near8 (antifreeze anti-freeze glycol ethyleneglycol water refrigerant (((heat near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2 exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant or (cooling near2 (fluid medium liquid gas vapor)))) (thermal near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (thermal near2 exchang\$3 near2 (fluid medium liquid gas vapor))))) and ((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 (power energy) near10 (process lamp ion electron) near10 (temperature near3 (wafer substrate workpiece plate susceptor pedestal support table chuck holder)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 12:14
70	41	5200023.URPN.	USPAT	2003/07/29 12:16
71	9	("3664942" "3718757" "4396478" "4675072" "4883560" "4913790" "4919542" "4936967" "4971653").PN.	USPAT	2003/07/29 12:46
72	11	4396478.URPN.	USPAT	2003/07/29 12:55
73	18	("4184480" "4409511" "4427378" "4680447" "4920918" "4945251" "5145716" "5152060" "5743643" "5762713" "5781693" "5790751" "5863334" "5960158" "6143079" "6148761" "6284051" "6435869").PN.	USPAT	2003/07/29 13:15
68	68	((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 temperature near12 (antifreeze anti-freeze glycol ethyleneglycol water refrigerant (((heat near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2 exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant or (cooling near2 (fluid medium liquid gas vapor)))) (thermal near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (thermal near2 exchang\$3 near2 (fluid medium liquid gas vapor))))) and ((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 (power energy) near10 (process lamp ion electron) near10 (temperature near3 (wafer substrate workpiece plate susceptor pedestal support table chuck holder)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 14:42

74	55	(((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 temperature near12 (antifreeze anti-freeze glycol ethyleneglycol water refrigerant (((heat near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2 exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant or (cooling near2 (fluid medium liquid gas vapor)))) (thermal near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (thermal near2 exchang\$3 near2 (fluid medium liquid gas vapor))))) and ((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 (power energy) near10 (process lamp ion electron) near10 (temperature near3 (wafer substrate workpiece plate susceptor pedestal support table chuck holder)))) not (((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near12 (((flow\$3 circulat\$3 suppl\$4) near3 (rate speed)) near8 (antifreeze anti-freeze glycol ethyleneglycol water refrigerant (((heat near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2 exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant or (cooling near2 (fluid medium liquid gas vapor)))) (thermal near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (thermal near2 exchang\$3 near2 (fluid medium liquid gas vapor))))) and ((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 (power energy) near10 (process lamp ion electron) near10 (temperature near3 (wafer substrate workpiece plate susceptor pedestal support table chuck holder))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 16:58
75	13	5605600.URPN.	USPAT	2003/07/29 16:27
76	13	5605600.URPN.	USPAT	2003/07/29 16:27
77	19	("4261762" "4457359" "4508161" "4533430" "4855017" "4903754" "4949783" "4963713" "5001423" "5093579" "5155331" "5191218" "5203958" "5267607" "5270266" "5290381" "5320982" "5366002" "5458734").PN.	USPAT	2003/07/29 16:27
78	1582	((control\$4 adjust\$4) near3 temperature near10 (wafer substrate workpiece plate susceptor pedestal support table chuck holder)).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 17:00
79	1017	(((control\$4 adjust\$4) near3 temperature near10 (wafer substrate workpiece plate susceptor pedestal support table chuck holder)).ti.) and (VLSI ULSI semiconductor wafer substrate (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 17:21
80	18	((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3 rais\$3) near5 (power energy) near10 (process lamp ion electron) near10 (temperature near3 (wafer substrate workpiece plate susceptor pedestal support table chuck holder))) and (((control\$4 adjust\$4) near3 temperature near10 (wafer substrate workpiece plate susceptor pedestal support table chuck holder)).ti.) and (VLSI ULSI semiconductor wafer substrate (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/29 17:21